

line 7, delete "(3)" (both occurrences);

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line 8, delete "(1)"; (both occurrences);

line 9, delete "(1) [sic]"; and

line 11, delete "Figure 2".

5 **IN THE CLAIMS:**

Please cancel claims 1-13, without prejudice, and substitute the following claims:

10 ~~14. A method for manufacturing metallic fine structures on a thin base layer made of a flexible organic material, said method comprising the steps of providing an auxiliary bearer made of a material that is at least largely transparent to laser radiation; applying a base layer onto the auxiliary bearer; producing a metallic fine structure on the base layer; and detaching the base layer from the auxiliary bearer by projecting laser radiation from a laser through the auxiliary bearer onto the base layer.--~~

15 --15. A method according to claim 14, wherein the auxiliary bearer is of quartz glass and the laser is an excimer laser having a wavelength of 248nm for the laser radiation.--

20 --16. A method according to claim 14, wherein the auxiliary bearer is made of borosilicate glass and the laser is an excimer laser having a wavelength of 350nm for the laser radiation.--

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--17. A method according to claim 14, which includes, before applying the base layer on the auxiliary bearer, applying an adhesive layer onto the auxiliary bearer.--

5 --18. A method according to claim 17, wherein the adhesive layer is made of titanium.--

--19. A method according to claim 18, wherein the adhesive layer is applied to the auxiliary bearer by sputtering.--

--20. A method according to claim 17, wherein the adhesive layer is applied by sputtering.--

10 --21. A method according to claim 14, wherein the base layer is applied in the form of a film.--

--22. A method according to claim 21, wherein the film is made of a thermostable polyamide.---

15 --23. A method according to claim 21, which includes applying a planarization layer of electrically insulating material on the base layer before producing the metallic fine structure.--

20 --24. A method according to claim 14, which includes applying an insulating layer on the fine metallic structure, forming a second layer of metallic fine structure on the insulating layer and then detaching the base layer from the auxiliary bearer.--

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--25. A method according to claim 24, which includes forming holes in the insulating layer before applying the second layer of metallic fine structure and forming through-contacts between the second layer of metallic fine structure and the first layer of metallic fine structure while forming the second layer of metallic fine structure.--

--26. A method according to claim 24, which includes, before detaching the base layer from the auxiliary bearer, applying a passivation layer onto the second layer of metallic fine structure.--

--27. A sensor arrangement for the acquisition of fingerprints, said arrangement comprising a thin base layer, a first metallic fine structure on a surface of the base layer, an insulating layer on the first metallic fine structure, said insulating layer having holes, a second metallic fine structure on said insulating layer having through-contacts to the first metallic fine structure and a passivation layer covering the second metallic fine structure.--

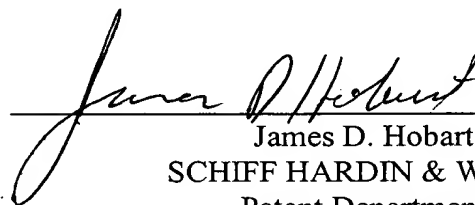
REMARKS

Claims 14-27 are presented for examination.

By this amendment, the specification has been amended to correct grammatical errors and to provide headings; claims 1-13, which were held allowable in the Preliminary Examination Report of May 29, 2000, have been rewritten to place them in form for examination in the United States Patent Office and to remove multiple-dependency.

It is submitted that the rewriting of claims 1-13 as claims 14-27 does not change the allowability set forth in the above-mentioned Preliminary Examination Report.

Respectfully submitted,

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